

**Laser Processing Systems** 



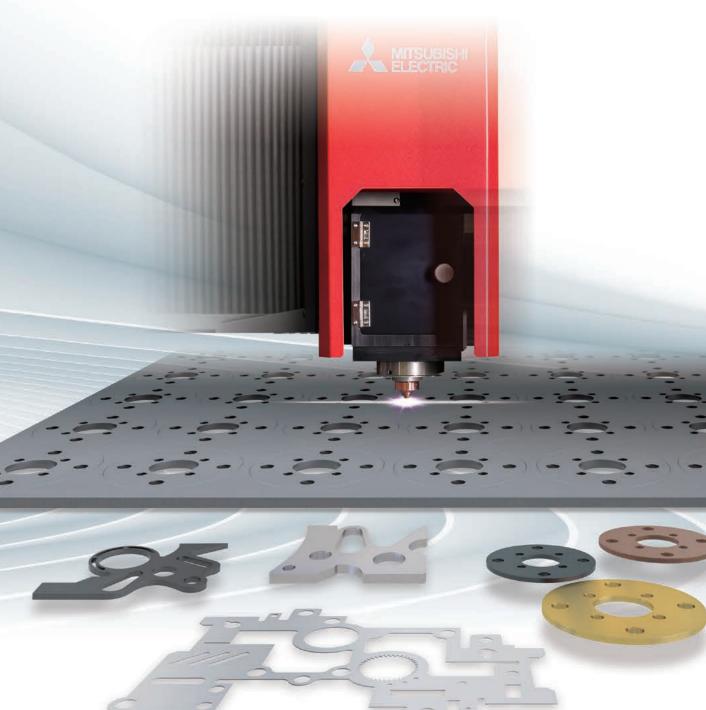
**FACTORY AUTOMATION** 

# CO<sub>2</sub> 2-Dimensional Laser Processing Systems ML3015SR-32XP



## Mitsubishi Electric **Laser Processing Machines**

supporting the world's production sites -





HEAD OFFICE: TOKYO BLDG., 2-7-3, MARUNOUCHI, CHIYODA-KU, TOKYO 100-8310, JAPAN NAGOYA WORKS: 1-14, YADA-MINAMI, 5-CHOME, HIGASHI-KU, NAGOYA 461-8670, JAPAN

K-KL2-6-C0200-A NA1601 Printed in Japan (IP)

New publication, effective Jan. 2016.

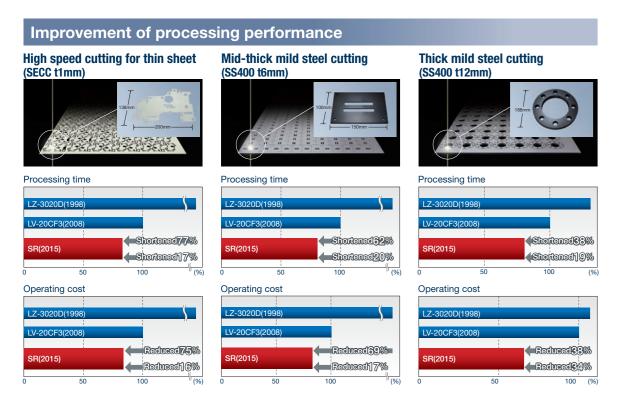
<sup>\*</sup> Not all the models are supported in all the countries and regions.

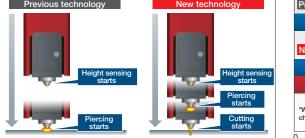
<sup>\*</sup> The machine specifications differ according to the countries and regions. Please check with your dealer.
\* The processing data provided in this brochure is for reference only.

**Laser Processing Systems** 

#### **Laser Processing Systems**

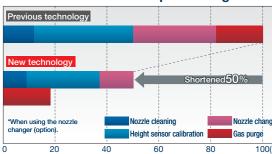
## **All-around machine** that covers all plate thickness



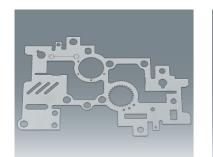


Minimizes the time before starting the piercing operation by performing the beam on and gas on processes before the height sensing completes.

#### Reduction in processing time of thin sheet Reduction in non-actual processing time



Total productivity has been improved with the high-speed and parallel operation of each movement before processing.

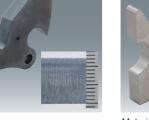


Material/Thickness



Galvanized steel (SECC)/t1mn

Mild steel (SS400)/t12mm



Stainless steel (SUS304)/t10mm \*When using f254mm(f10") lens (option)

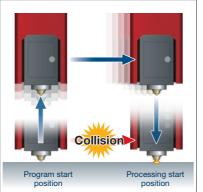
# Reliable and comfortable operation attained with the latest technology

#### Support for reliable operation

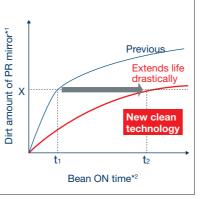
# Night mode

Switching to the night operation with the preset time is available. Reduction in pallet running noise considering the surrounding environment. Reduction in contact with the workpiece by changing the movement of the processing head.

## Upward Z-axis at program start New clean technology



Z-axis rises automatically at the same time with the program start. Reduces the risk of processing head collision and supports reliable operation regardless of



Enhanced clean technology extends the life of the PR mirror drastically.

- \*1: Dirt limit value X of PR mirror differs depending on the processing contents, required specifications, etc.
- \*2: Time of t<sub>1</sub> and t<sub>2</sub> that reaches to the dirt limit value of PR mirror differs depending on the deterioration condition of the

## Comfortable operability

## Simple processing condition



High quality processing regardless of proficiency is possible by selecting the similar picture to processing status.

#### Simple program editor



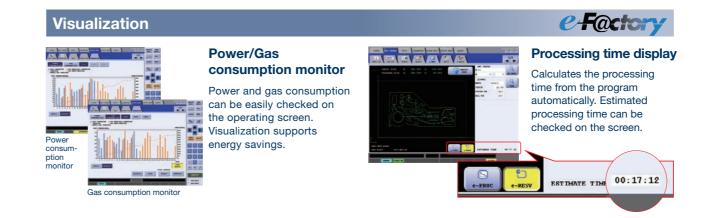
Allows the change of program and processing condition numbers easily while checking the shape on the graphic

### **Active control**



Adjusts the processing condition by a dial while looking at the processing.

## Visualization supports energy saving / production plan and reduces operating cost



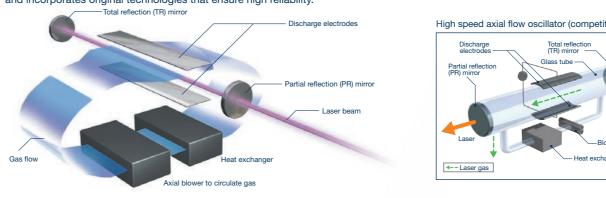
#### Reduces operating cost and supports energy savings



Cost during standby has been reduced by up to 93% by shutting down each operation in stages after

#### 3-Axis cross gas flow excitation system oscillator

Mitsubishi Electric's resonator series realizes further enhancements in performance and stability, and incorporates original technologies that ensure high reliability.





The Just-on-time discharge method and the seal-off operation significantly reduce power consumption and gas consumption. Also, the simple oscillator structure with few maintenance parts reduces the total operating cost.

# 2 4 6 8 10 12 14 16 18 20 22 \*The above are processing capabilities based on special conditions. The acceptance criteria are as stated in the specification

- The actual performance/quality may vary depending on the surface condition and deviation in the material composition even it \*Variations in processing performance/quality may occur depending on the part geometry.

ons				
	f125mm (f5") lens			
	f254mm (f10") lens			
	Magnetic damage reduction		Control unit	Network download
ssing	Automation pack (Magnetic Damage Reduction + Nozzle Changer)			
ne	Work clamp (manual)			CamMagic LA (CAD/CAM exclusively for lasers)
	Work lifter	7		Linked nesting
	Barcode reader	1	Solutions	Linked DXF conversion
	FRG(F-CUT Route Generator)	]		Linked e-mail notification additional features
		_		BANKIN Navigator(Production control support)

Model	name		ML3015SR
Drive system			Flying optic (X-axis, Y-axis:light transfer)
Control system			Simultaneously 3-axis (X-Y-Z) control (Z-axis height control is also possible)
Workpiece dimensions (mm)			3050×1525
Pallet load weight (kg)			950
Workp	iece suppo	ort height (mm)	880
X-axis (mm) Y-axis (mm) Z-axis (mm)		X-axis (mm)	3100
		Y-axis (mm)	1565
		Z-axis (mm)	150
	Rapid feedrate	XY-axis(m/min)	Maximum 100
Speed		Z-axis(m/min)	Maximum 65
	Maximum processing feedrate(m/min)		50
	Positioning accuracy	XY-axis(mm)	0.05/500
ccuracy		Z-axis(mm)	0.1/100
	Repeatability (mm)		±0.01(X,Y-axis)
Processing head			Auto-focus preset head
			Processing lens (mm) ø50.8{ø2.0"}×f190.5{f7.5"}
Power requirement (kVA)		ent (kVA)	8
External dimensions		ons	9918×3134×1956
Weight Machine weight (excluding oscillator)		eight (excluding oscillator)	Approx. 7500

Oscillator specifications				
Model name		ML32XP		
Excitation me	thod	3-axis SD excitation cross flow oscillator		
	Pulse peak output (W)	3200		
	Rated output (W)	2700		
Laser output characteristics	Beam mode	Lower order (TEM01*main component)		
	Power stability (%)	±1 or less during power control (relative to rated output)		
	Output power adjustable range (%)	0 to 100		
Laser gas cor	nposition	CO2:CO:N2:He = 8:4:60:28		
Laser gas cor	nsumption( let/hr)	Approx. 1		
Power require	ement (kVA)	41		
External dime	ensions (mm)	2040×450×1620		
Weight (kg)		Approx. 1200		
Cooling s	vstem specification	ns		

ng method	Air	
er requirement (kVA)	21	
ng capacity (kW)	45	
nal dimensions (mm)	2390×934×1772	
ht (kg)	Approx. 850	

Control system specifications				
Display screen	15" TFT (touch panel)			
Hard disk (GB)	20			
Program input method	Screen creation, USB (ver.2.0), Ethernet			
Operation method	Memory operation, HD direct operation			

